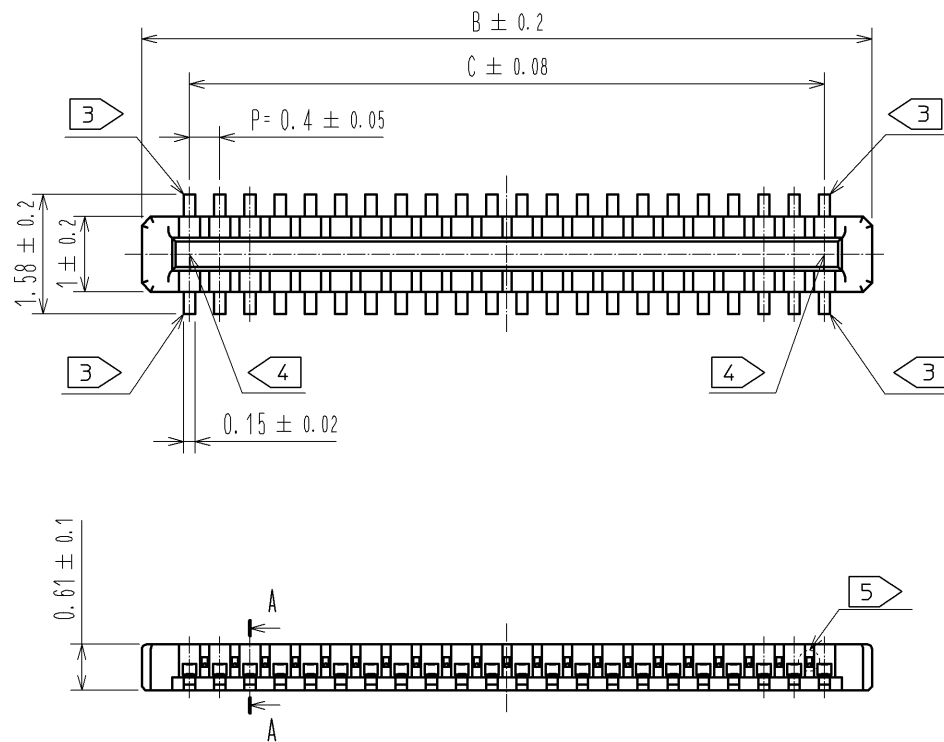
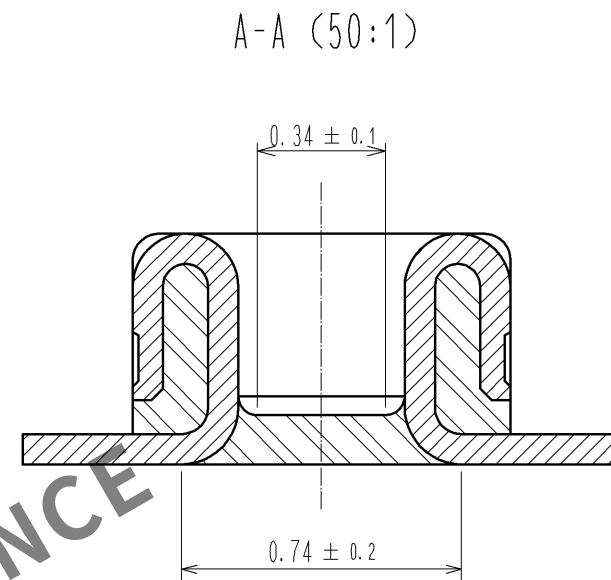


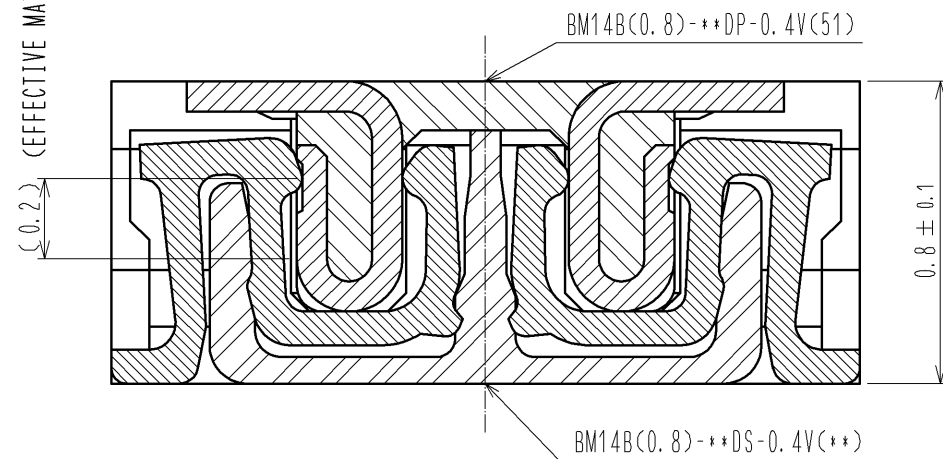


- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 . CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3 . EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
THEY CAN BE USED ALSO AS A SIGNAL CONTACT.
4 . HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5 . A PART OF THE WALL COULD BE NOTCHED.

PART No.	CODE No.	B	C
BM14B(0.8)-10DP-0.4V(51)	CL684-8010-0-51	3.66	2.4
BM14B(0.8)-12DP-0.4V(51)	CL684-8042-7-51	4.06	2.8
BM14B(0.8)-20DP-0.4V(51)	CL684-8011-3-51	5.66	4.4
BM14B(0.8)-22DP-0.4V(51)	CL684-8047-0-51	6.06	4.8
BM14B(0.8)-24DP-0.4V(51)	CL684-8012-6-51	6.46	5.2
BM14B(0.8)-30DP-0.4V(51)	CL684-8013-9-51	7.66	6.4
BM14B(0.8)-34DP-0.4V(51)	CL684-8014-1-51	8.46	7.2
BM14B(0.8)-40DP-0.4V(51)	CL684-8015-4-51	9.66	8.4
BM14B(0.8)-50DP-0.4V(51)	CL684-8016-7-51	11.66	10.4
BM14B(0.8)-60DP-0.4V(51)	CL684-8002-2-51	13.66	12.4

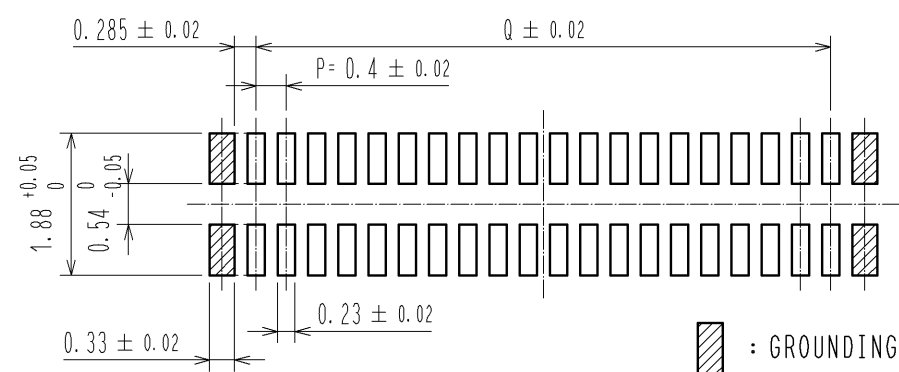


ENGAGEMENT FIGURE (50:1)



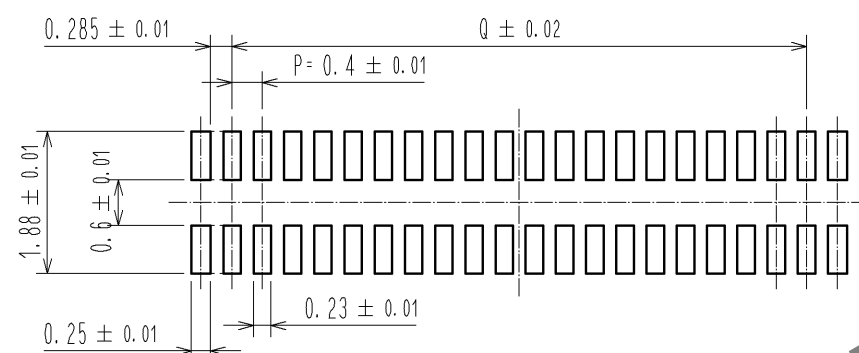
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 1	DESCRIPTION OF REVISIONS DIS-H-008082	DESIGNED SH. HOSODA
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	09.11.24	DRAWING NO. EDC3-322328-04	DATE 13.08.03
		CHECKED : WR. FUKUCHI	09.11.24	PART NO. BM14B(0.8)-*DP-0.4V(51)	
		DESIGNED : YH. HASEGAWA	09.11.20	CODE NO. CL684	
		DRAWN : YH. HASEGAWA	09.11.20		

◆ RECOMMENDED PCB LAYOUT

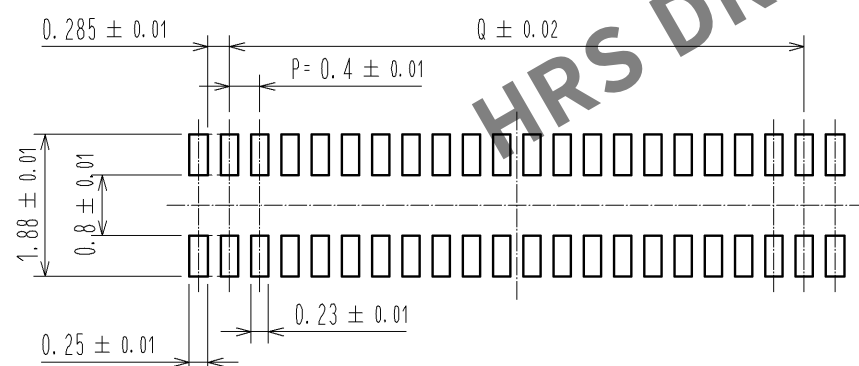


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm

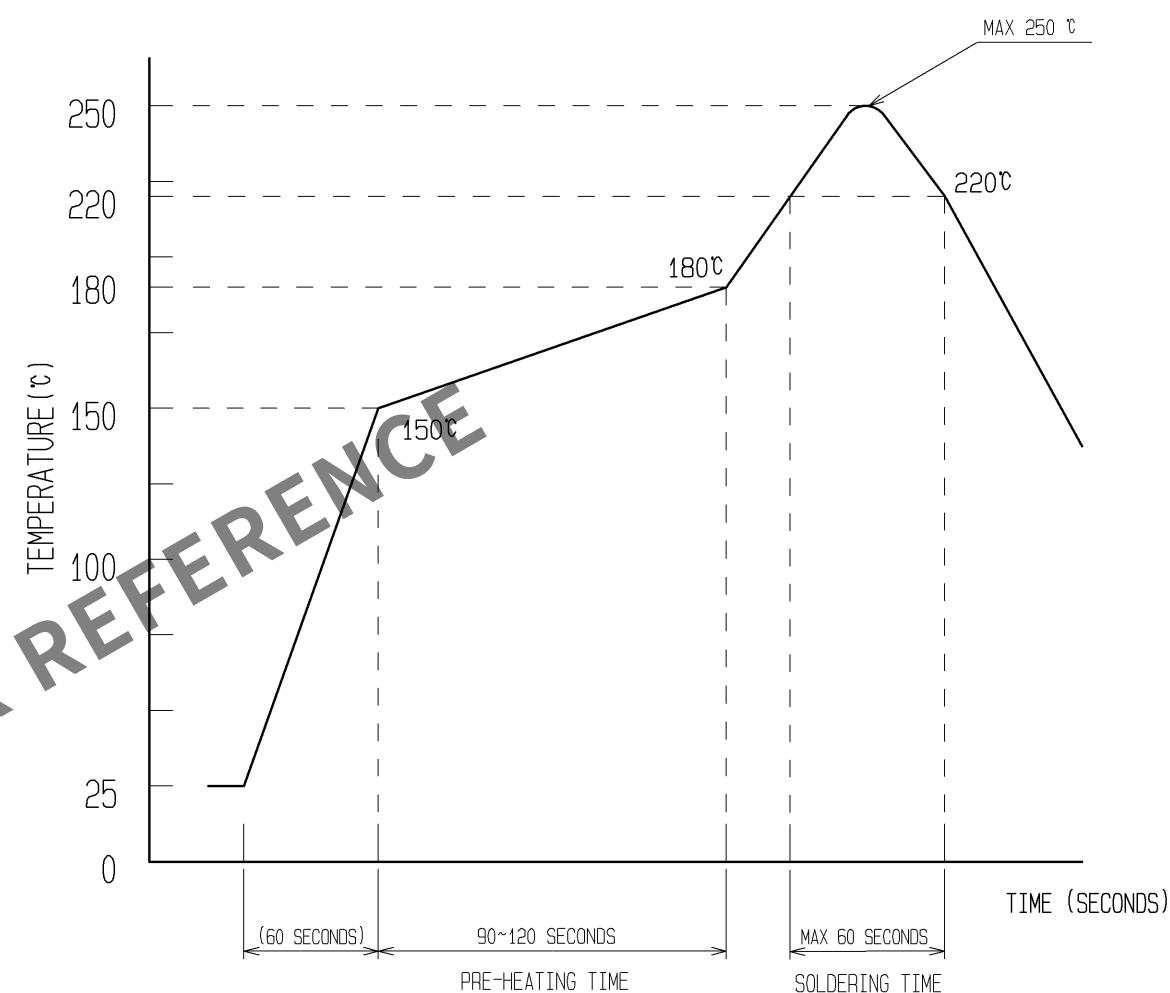


METAL MASK THICKNESS : 120 μm



PART No.	Q
BM14B(0.8)-10DP-0.4V(51)	1.6
BM14B(0.8)-12DP-0.4V(51)	2.0
BM14B(0.8)-20DP-0.4V(51)	3.6
BM14B(0.8)-22DP-0.4V(51)	4.0
BM14B(0.8)-24DP-0.4V(51)	4.4
BM14B(0.8)-30DP-0.4V(51)	5.6
BM14B(0.8)-34DP-0.4V(51)	6.4
BM14B(0.8)-40DP-0.4V(51)	7.6
BM14B(0.8)-50DP-0.4V(51)	9.6
BM14B(0.8)-60DP-0.4V(51)	11.6

⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

⑥ THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-322328-04
PART NO.	BM14B(0.8)-*DP-0.4V(51)
CODE NO.	CL684

